

PHOTONIC SIDE-CHANNEL ANALYZER: ENABLING SECURITY-AWARE PHYSICAL DESIGN METHODOLOGY

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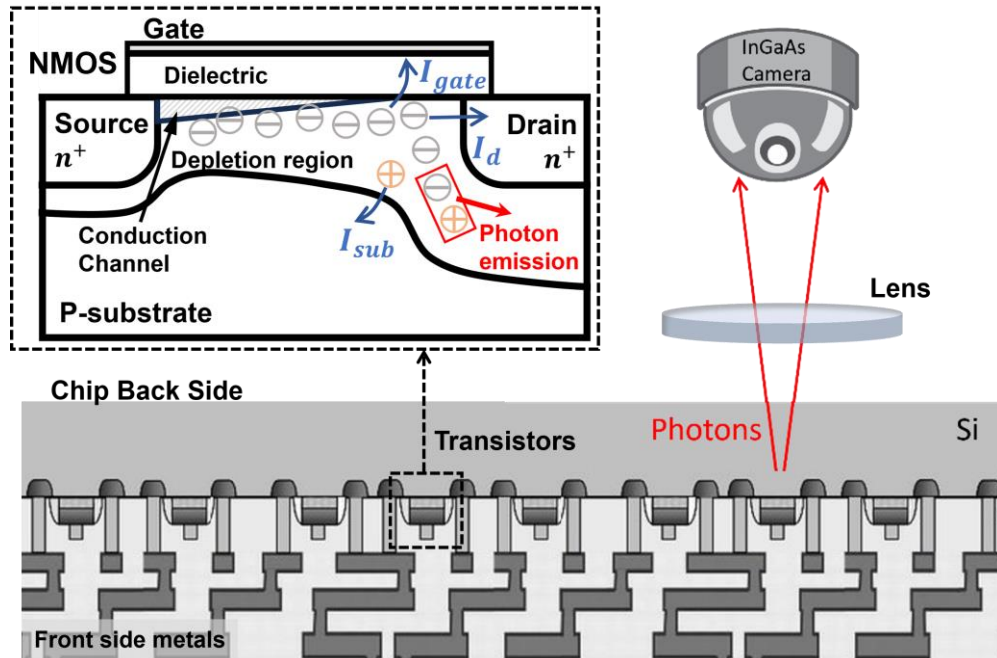
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Outline

- Introduction:
 - Photon emission (PE) as a side-channel threat
- Photonic Side-Channel Simulation Framework:
 - Standard-cell PE library generation
 - Circuit level PE Heatmap generation
 - PE side-channel analysis
- Measurement & Comparison:
 - Validating simulated PE heatmaps against real chip measurements
- Conclusion

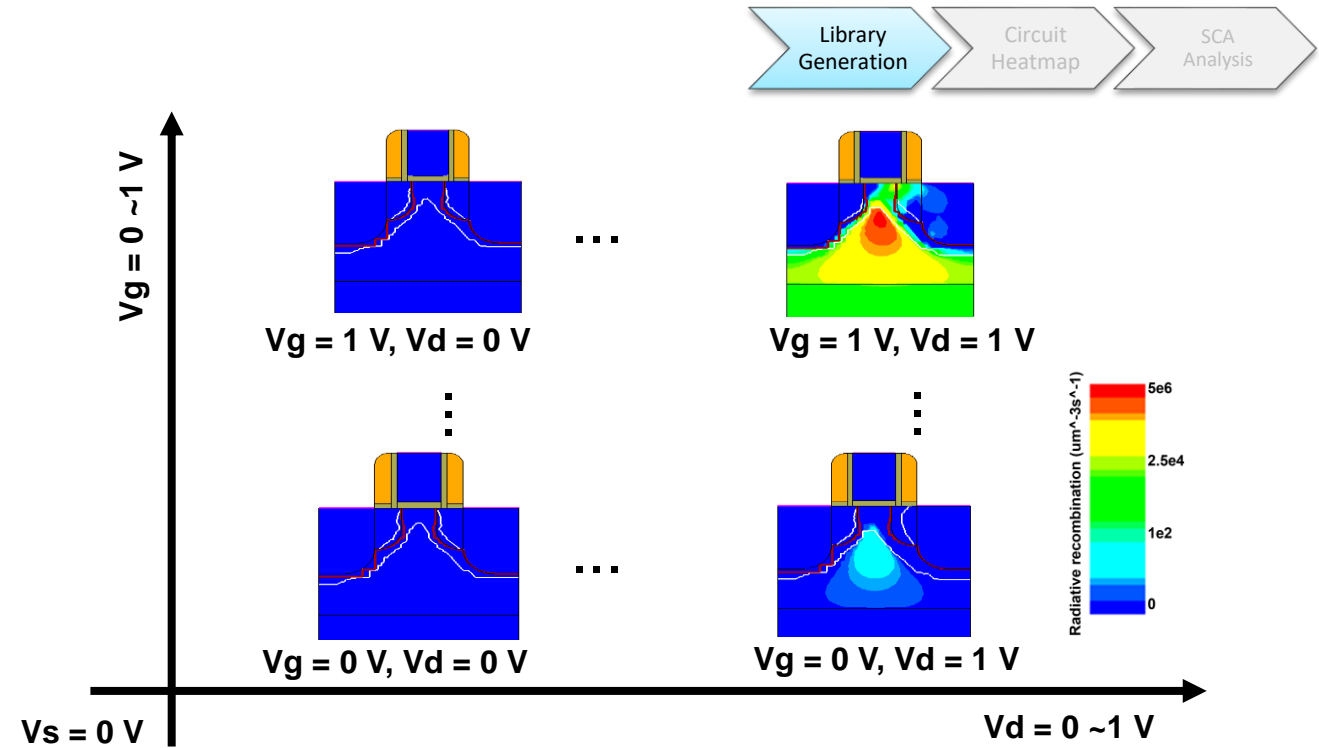
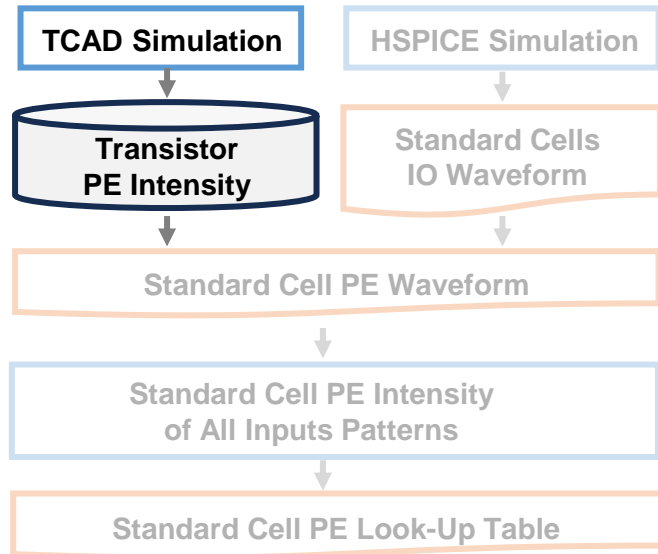
Introduction

Photon Emission in Integrated Circuit



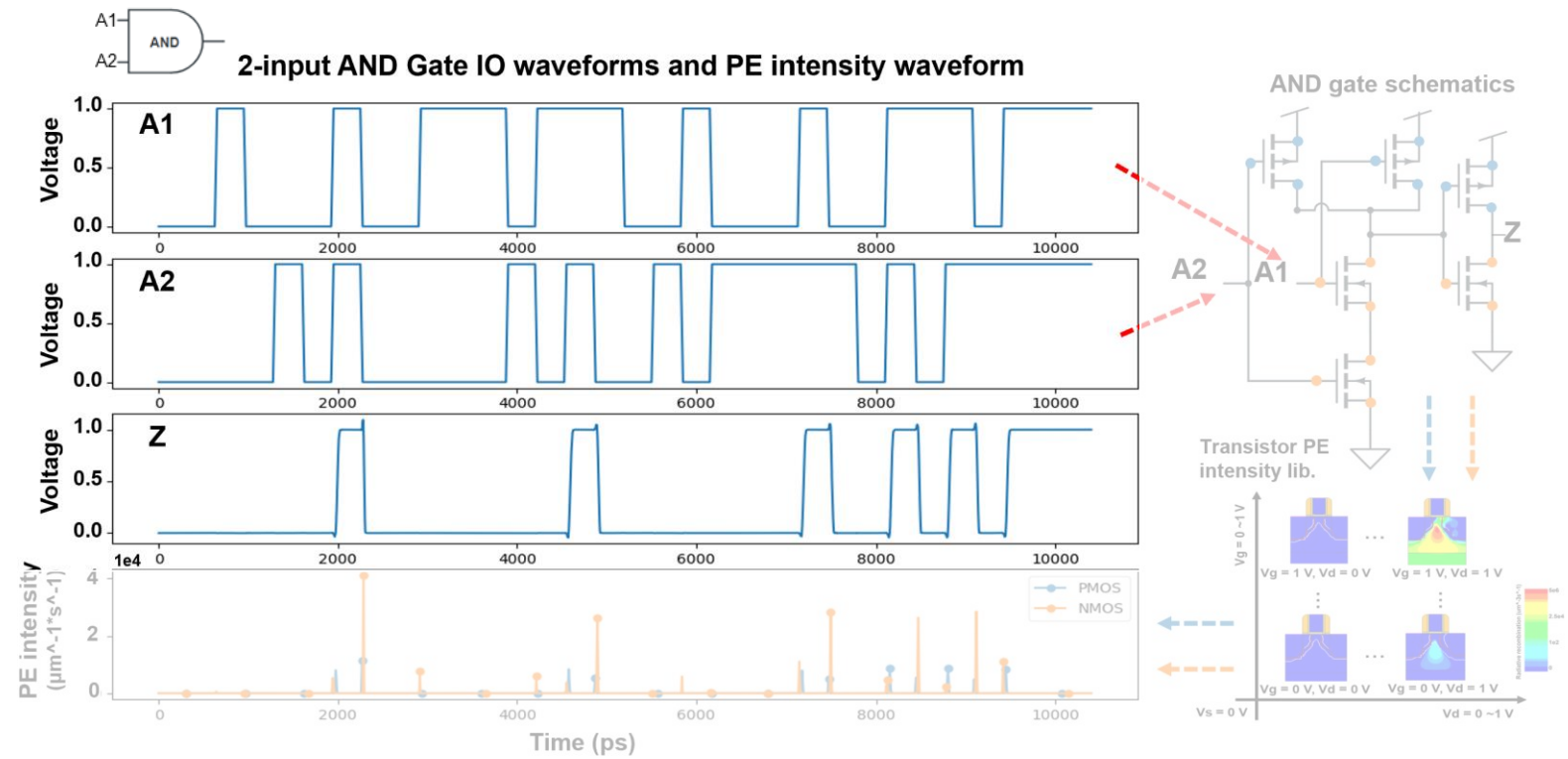
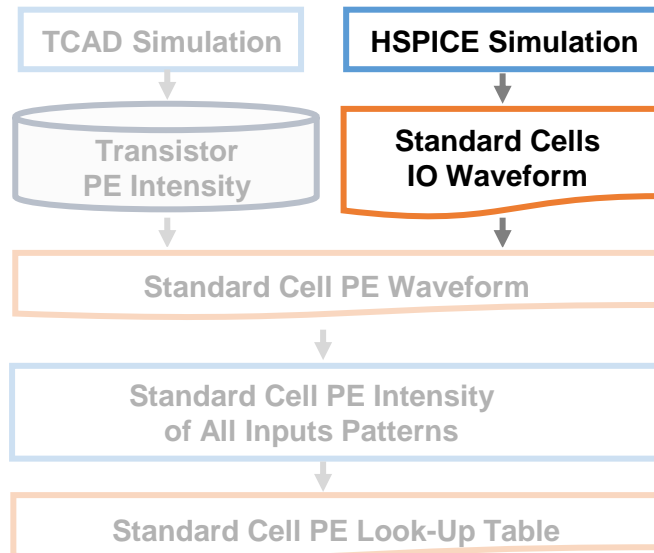
- Occurs during transistors switching due to electron-hole recombination at the drain region.
- Emits some energy as photons through radiative recombination.
- Passes through the silicon substrate and is captured by a measurement lens.
- Peaks in the saturation region, with intensity correlating to switching activity, making it a potential side-channel leakage source.
- Requires pre-silicon security analysis to mitigate leakage risks early in the design process.

TCAD Simulation



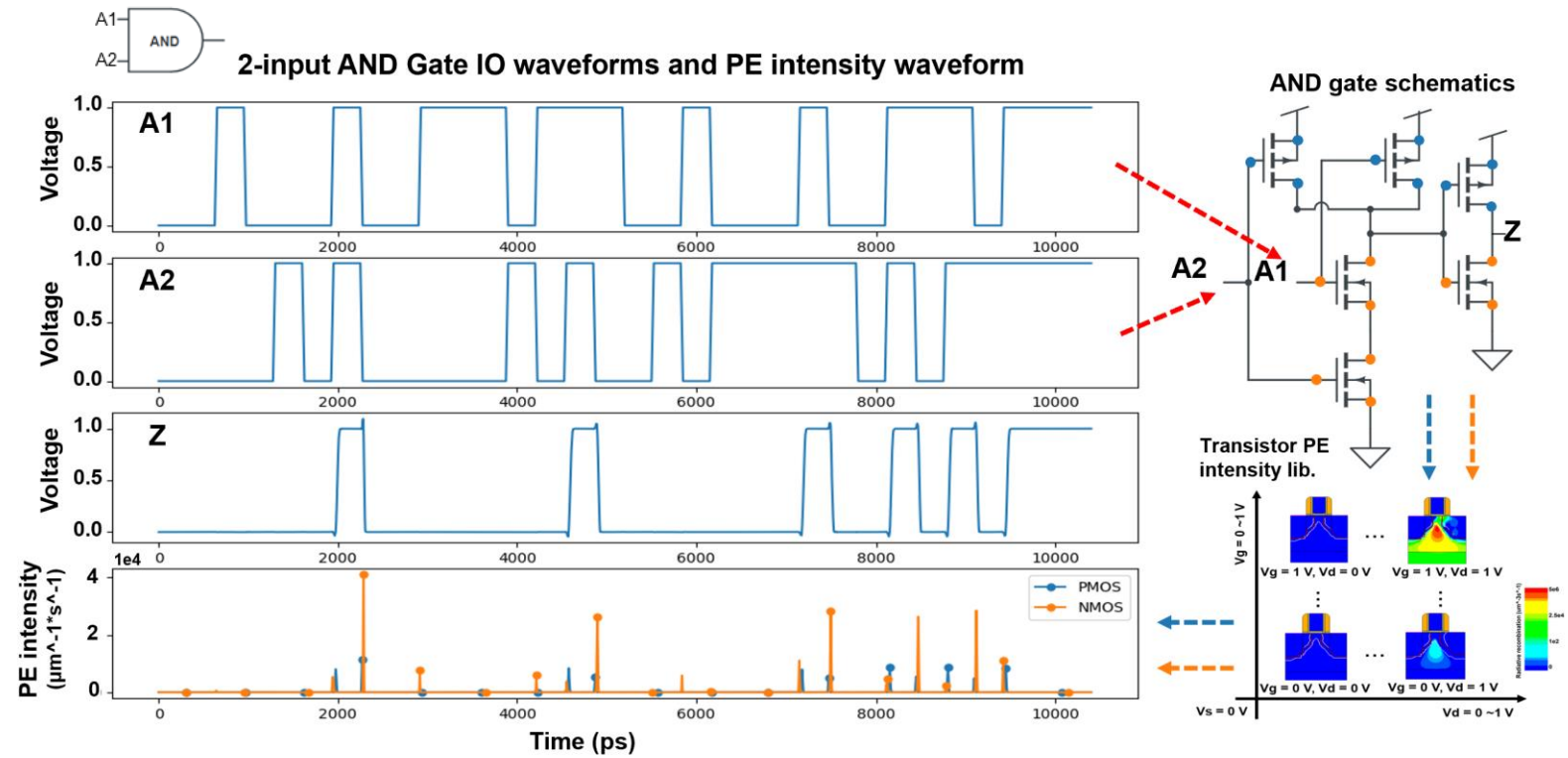
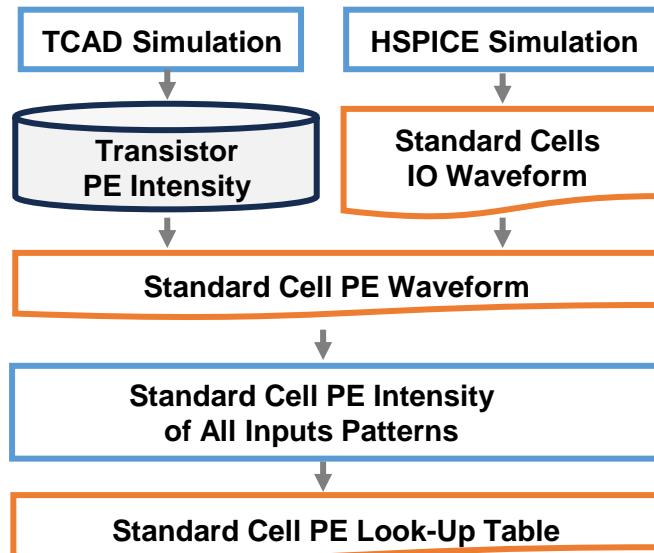
- Develop a Technology Computer-Aided Design (TCAD) model for a representative 40nm P-MOSFET and N-MOSFET.
- Simulate radiative recombination of electron-hole pairs under varying device biasing conditions.
- Generate a PE look-up table using the average radiative recombination (RR) rate, mapped to device biasing parameters.

HSPICE Simulation



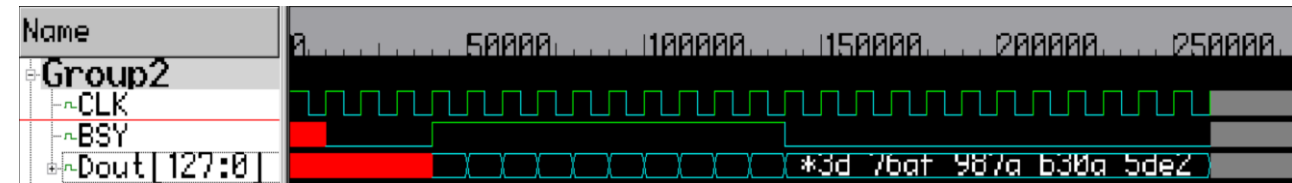
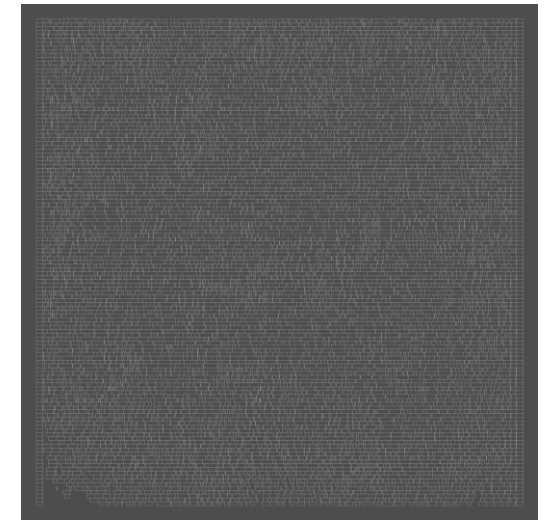
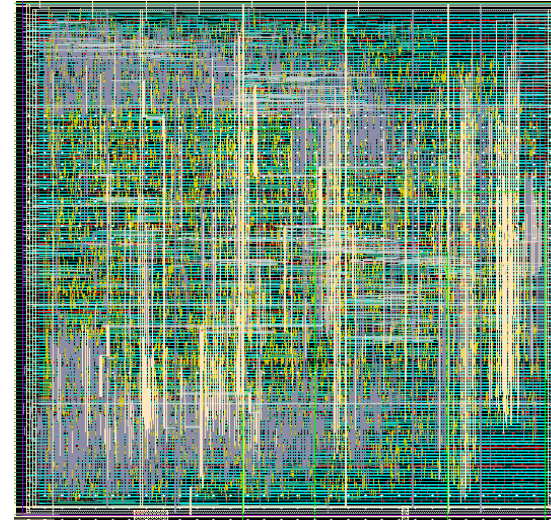
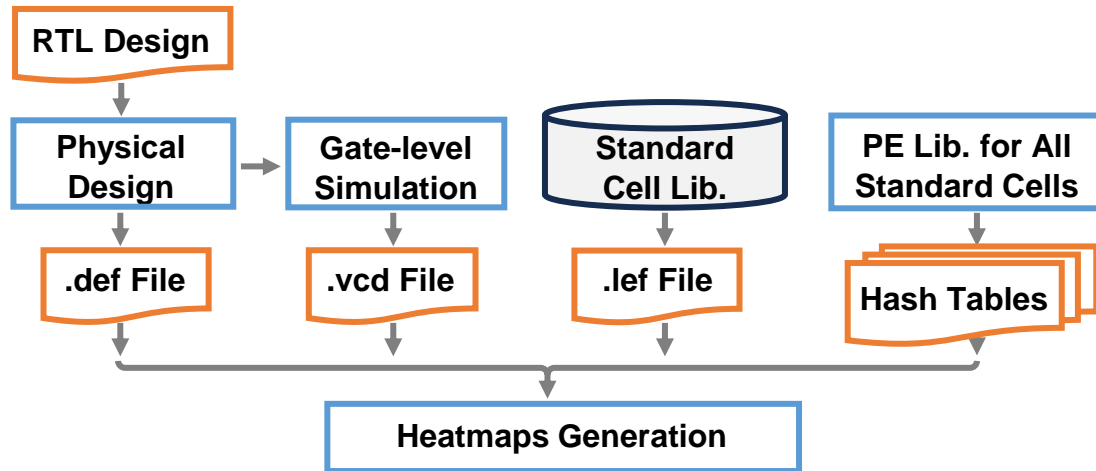
- Generate all possible input transition vectors for standard cells.
- Simulate all input transitions using HSPICE to analyze switching behavior.

Standard Cell PE Look-Up Table



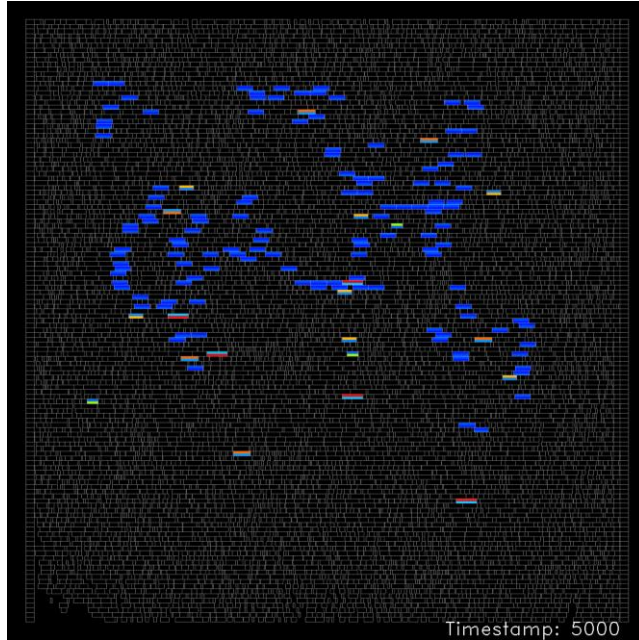
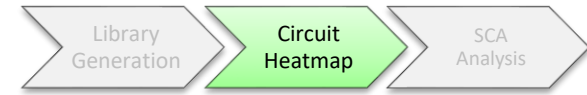
- Reference TCAD results to determine photon emission intensity for all input transition vectors.
- Construct a hash table for each standard cell, mapping NMOS and PMOS emission intensity to corresponding input transitions.
- Form the Standard Cell PE Library, where the hash table enables fast lookup of emission intensities during circuit-level analysis.

PE Heatmap Generation



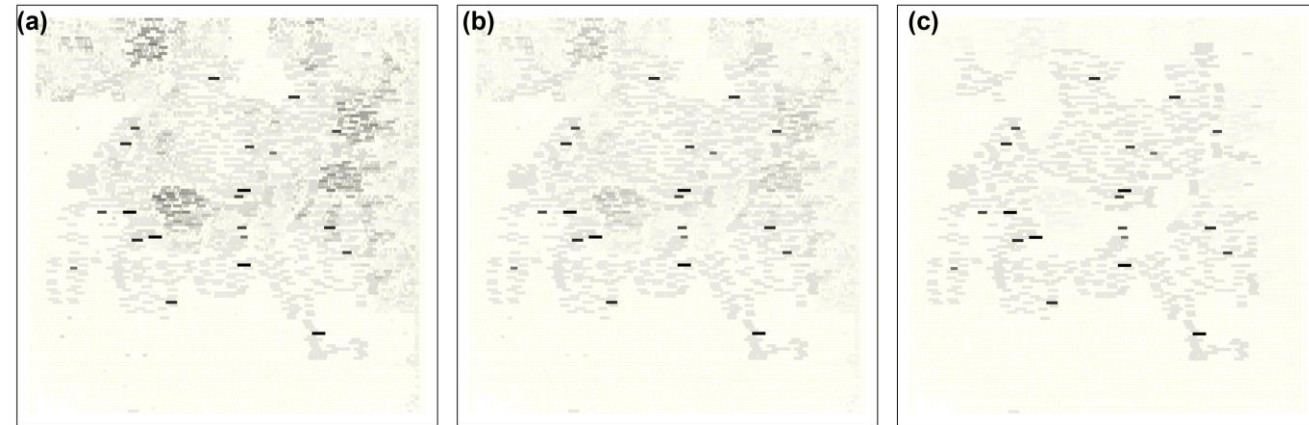
- Extract circuit information (die dimensions, standard cell attributes) from library files.
- Track input vector transitions for all standard cells during post-layout simulation.
- Generate photonic heatmaps by referencing the Standard Cell PE Library to assign emission intensities over time.

Simulated PE Heatmap



Time-Resolved PE Heatmap

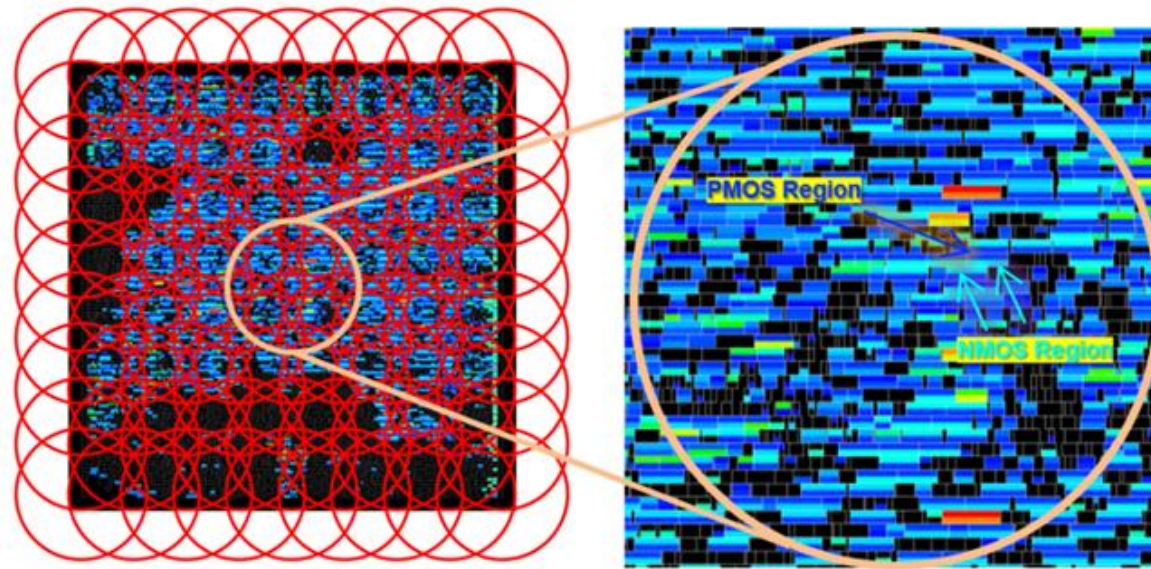
- Captured PE variations across different clock cycles during AES encryption, providing spatial and temporal insights.



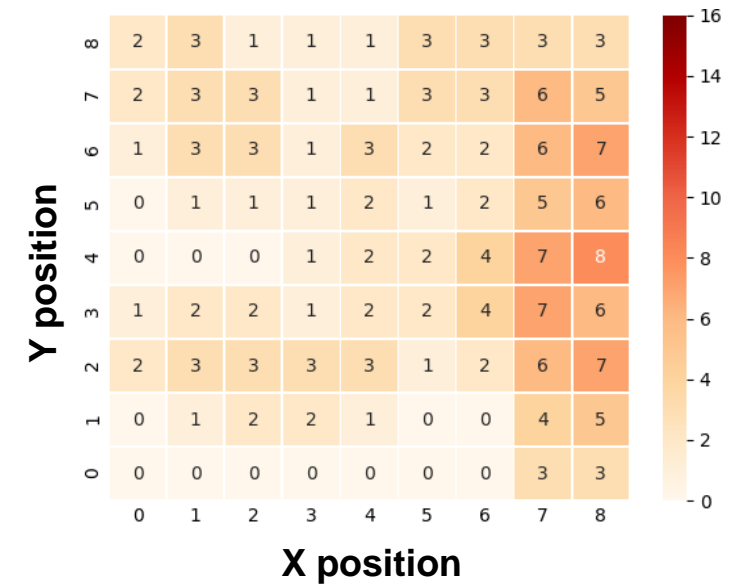
Time-Accumulated PE Heatmap

- Shows PE emissions over extended operation times (15, 25, 150 ms), where a few cells begin to dominate.
- As accumulation increases, emission details in less active regions are lost, with darker areas indicating higher PE intensity.

PE Side-Channel Analysis

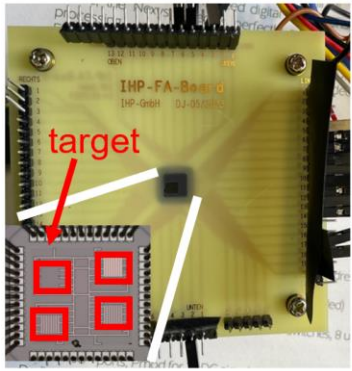


Number of decrypted Key Byte with 4000 traces at each attacking locations

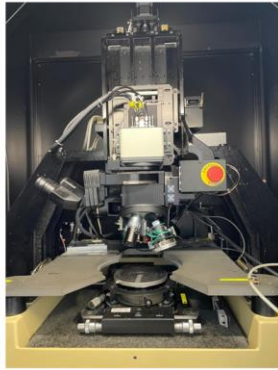


- Overlay probing grid on the AES core to analyze photon emission distribution.
- Aggregate PE values from all standard cells within each probing area.
- Calculate PE intensity at each location and run a side-channel attack to analyze leakage.
- Mitigate leakage by redesigning the most vulnerable areas to enhance security.

Measurement & Comparison



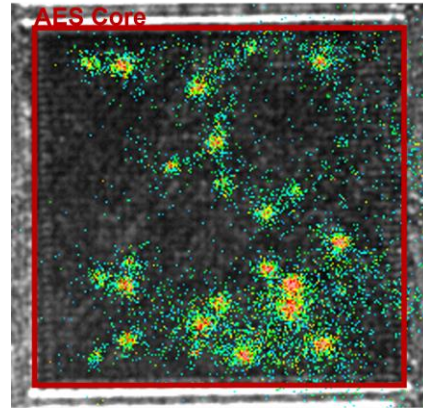
(a) Testchip



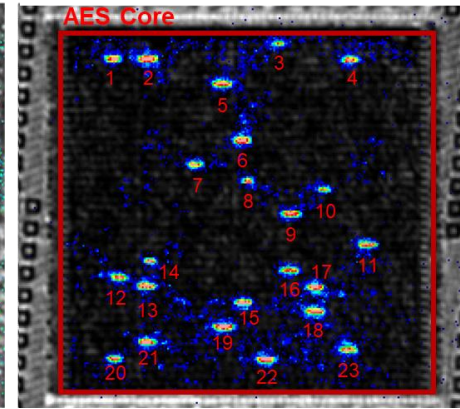
(b) Microscopy



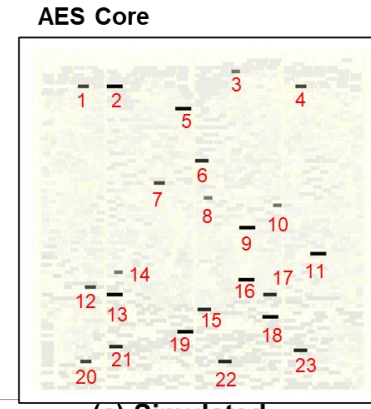
(c) Hamamatsu PHEMOS 1000



(a) Measured PE at 60s



(b) Measured PE at 300s




(c) Simulated accumulated PE map

- The PE intensity of the AES core is measured using a Microscopy System equipped with an InGaAs camera inside the Hamamatsu PHEMOS-100.

- Repeat encryption operations and measure PE for 60s and 300s.
- 60s Measurement: High noise, making emission details harder to distinguish.
- 300s Measurement: More stable, showing strong hotspot consistency with the simulated PE map but losing finer details over time.

Conclusion

- Developed an analysis framework to assess PE vulnerabilities in digital ASIC circuits during pre-silicon design.
 - Simulated time-resolved PE maps for a 128-bit AES core and conducted localized CPEA analysis, showing that finer attack granularity increases leakage risks.
 - Validated framework accuracy by comparing simulated and measured PE maps on a 40nm chip, confirming its reliability for security evaluations.
 - Enables early identification of vulnerable regions and facilitates mitigation strategies to reduce side-channel leakage.
 - Enhances security-aware design by integrating side-channel analysis into the design phase, improving circuit security and reliability.
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